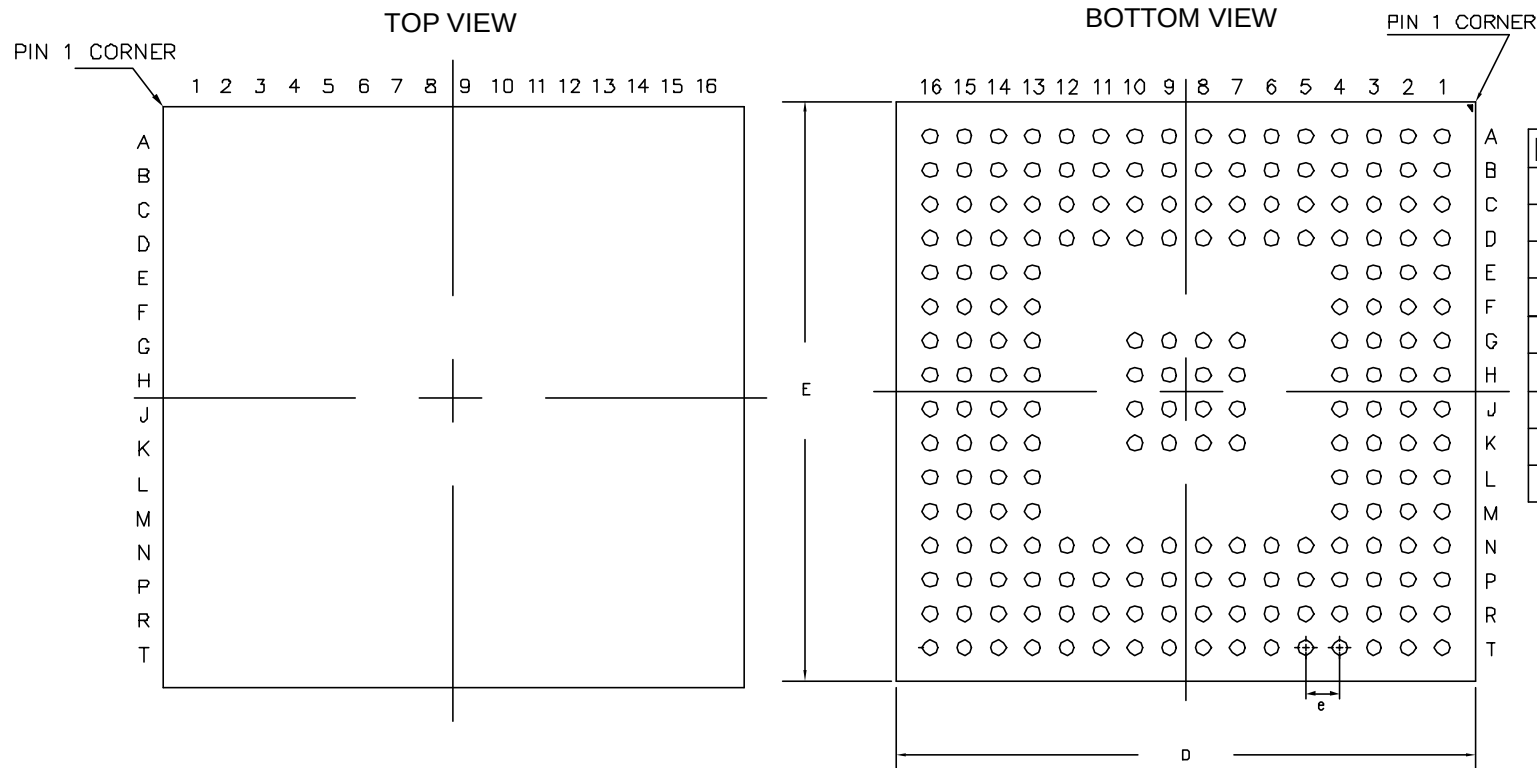




Dimension	MIN	MAX
A	-	1.40
A1	0.30	0.50
A2	0.53 REF	
D	16.90	17.10
E	16.90	17.10
b	0.40	0.60
e	1.00	
N	208	
Conforms to JEDEC MO-192		

NOTES: -

1. Controlling dimensions are in MM.
2. Seating plane is defined by the spherical crown of the solder balls.
3. Not to scale.
4. N is the number of solder balls
5. Substrate thickness is 0.36 MM.

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Previous package codes

Package Code GD

Package Outline for
208ball LGA
17x17x1.4mm Max

GPD00802